



Nano-materials Based 3D Electronics

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Message from the Guest Editor

Dear Colleagues,

As Moore's law is going to hit the wall imposed by quantum effects, the further miniaturization of microelectronic systems is expected to be driven by 3D heterogeneous integration. In order to realize high-density and high-performance integration in a 3D fashion, stacking chips in the vertical direction is a key step. To enable communication among stacked chips, new materials and semiconductor processes have to be developed. In this perspective, nano-materials have attracted a great deal of attention due to their special electrical, mechanical, thermal and chemical properties. In addition, high density integration of components in microsystems places the challenging-enough thermal management problem on fire. In this Special Issue of Electronics, we would like to report on the most recent progresses in 3D integration of microsystems. Contributions on all dimensions of 3D integration are welcome.

Dr. Yifeng Fu





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Message from the Editor-in-Chief

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